

●USP-4 Power Dissipation

Power dissipation data for the USP-4 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as the reference data taken in the following condition.

1. Measurement Condition

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm² in one side)

Copper (Cu) traces occupy 50% of the board area

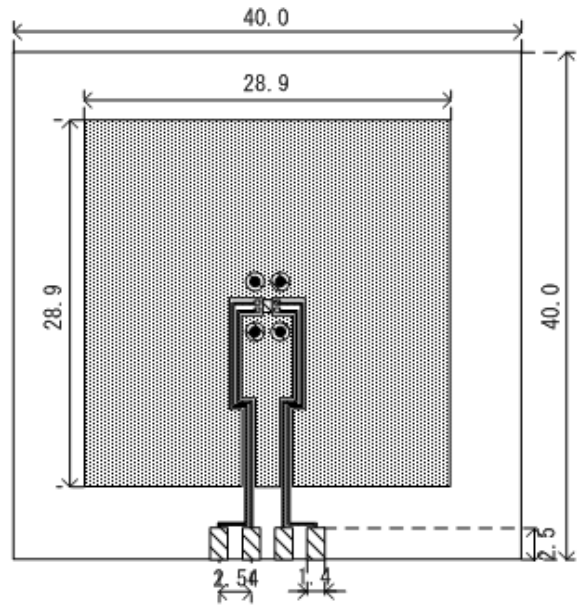
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

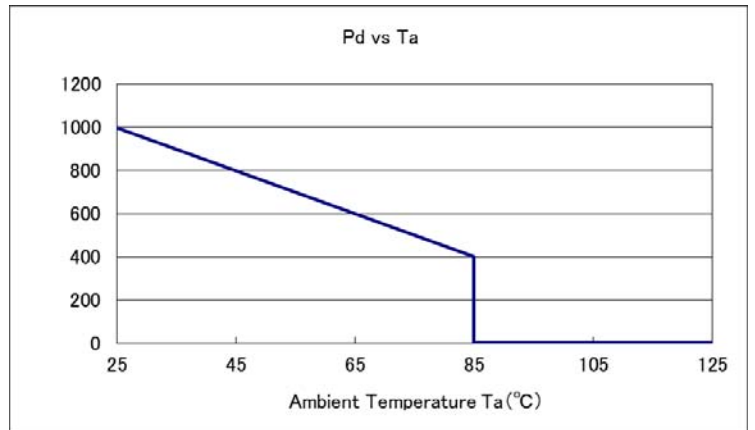


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature (85°C)

Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	100.00
85	400	



3. Power Dissipation vs. Ambient Temperature (105°C)

Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	100.00
85	200	

